XCede® I/O

Amphenol ICC's XCede® I/O interconnect system is comprised of a 32 position, variable pitch connector built for use in high speed serial applications. Each port offers 4 channels to increase port density which contributes to more board real estate and immense cost savings. The XCede® I/O connector supports next generation 100G+ applications and transmits up to 25 Gb/s per serial-lane. It features a stamped and formed contact design providing improved mechanical durability and resonance dampening features for superior performance. The design minimizes crosstalk and transmission line impedance discontinuity across the connector interface.

TARGET MARKETS

TECHNICAL INFORMATION

MATERIAL

- Housing: Black color, Glass-reinforced, lead-free solder reflow process compatible thermoplastic
- Contacts Base Material: Phosphor Bronze
- Plating Solder Tails: Matte tin over Nickel
- Plating Mating Tails: Gold
- Resonance Dampening Feature: Conductive Polymer

MECHANICAL PERFORMANCE

- Durability: 250 mating cycles
- Mating Force: 55.5 N max.
- Contact Normal Force: 50 grams
- Latch Retention Force: 50 N min.

ELECTRICAL PERFORMANCE

- Maximum Voltage: 30 VDC per contact
- Maximum Current: 0.5 A per contact
- Differential Impedance: 100Ω +/- 10Ω
- Insulation Resistance: 1e3 MΩ min. between adjacent contacts
- DMV: 300 V AC

ENVIRONMENTAL

- Operating and (Storage) Temperature: -40°C to +85°C
- RoHS & Halogen-Free

TOOLING INFORMATION

- Configurations: 1X1, 1x2
- Latch Internal Plug Retention: Pin-In-Hole Options Available

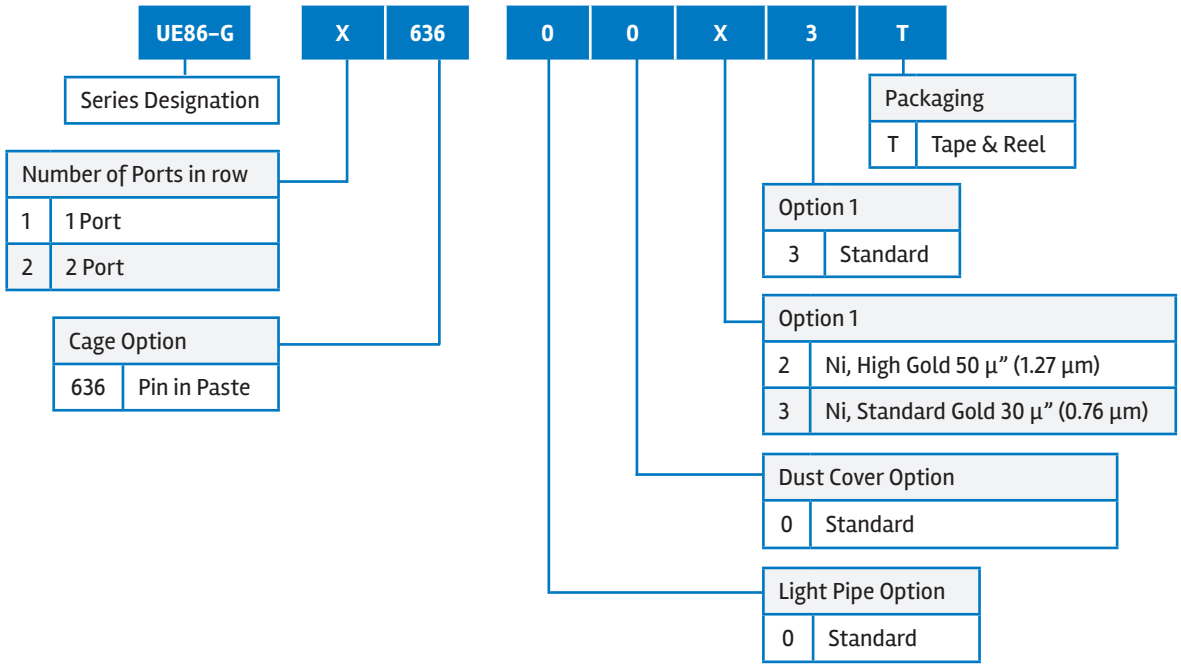
TARGET MARKETS/APPLICATIONS

Network Interface Cards

Cellular Infrastructure
Hubs
Storage
Servers

Test and Measurement Equipment

PART NUMBER SELECTOR



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